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<u>L9</u>	image with boundar\$3 with (orientation or direction)	1474	<u>L9</u>
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<u>L11</u>	L10 same (line or edge)	19	<u>L11</u>
<u>L12</u>	(primary near2 angle) same (secondary near2 angle)	294	<u>L12</u>
<u>L13</u>	L12 same boundar\$3	3	<u>L13</u>

<u>L14</u>	L12 same (rectangular or rectangle)	2	<u>L14</u>
<u>L15</u>	(finding or find or finding or finder or locating or locater or locator or search\$3) near5 (rectangular or rectangle)	1794	<u>L15</u>
<u>L16</u>	L15 same image	319	<u>L16</u>
<u>L17</u>	L16 same boundar\$3	39	<u>L17</u>
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TITLE: Method and apparatus for location and inspecting a two-dimensional image including co-linear features

Brief Summary Text (12):

The grouping technique for searching for correspondence between model features and image features involves using a small, selected subset of image features. The image features are ones that are most likely to belong to a subset of a set of features comprising the model. For example, a vision system might be implemented in an application wherein it is desirable to find a particular rectangular object in the scene or image, e.g. a microchip. Although the captured image contains many objects, grouping could be applied by having the vision system select all groups of line segments from the image, and more particularly all groups of line segments that are at right angles to each other. The subsets or smaller groups of features, e.g. line segments at right angles to each other, would then be used to match to the chip model, rather than using the entire set of line segments.